

## Tripolar overvoltage protection for network interfaces

### Features

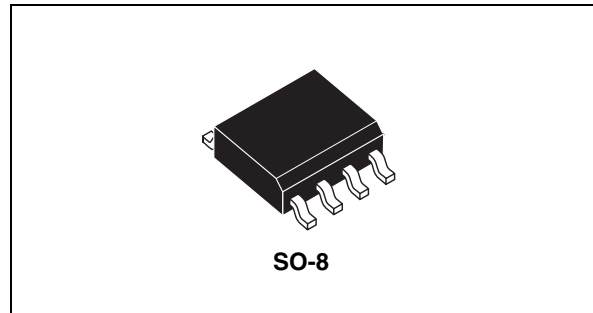
- Triple crowbar protection
- Low capacitance
- Low holding current:  $I_H = 30$  mA minimum
- Surge current:  
 $I_{PP} = 200$  A, 2/10  $\mu$ s  
 $I_{PP} = 30$  A, 10/1000  $\mu$ s

### Benefits

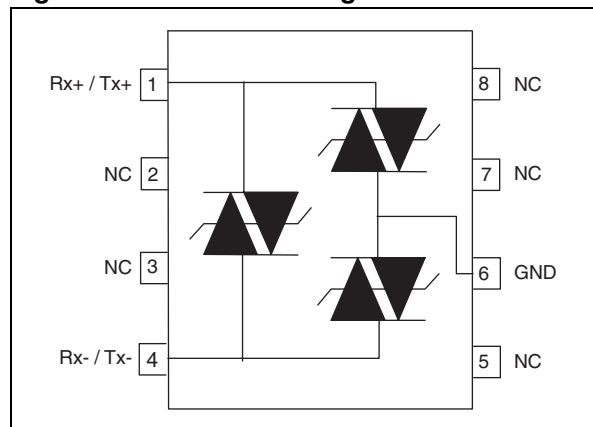
- Trisil™ technology is not subject to ageing and provides a fail safe mode in short circuit for a better protection.
- This device can be used to help equipment to meet main standards such as UL1950, IEC 950 / CSA C22.2 and UL1459.
- Trisils have UL94 V0 approved resin.
- SO8 package is JEDEC registered.
- Trisils comply with the following standards GR-1089 Core, ITU-T-K20/K21, VDE0433, VDE0878, IEC 61000-4-2.

### Applications

Dedicated to data line protection, this device provides a tripolar protection function. It ensures the same protection capability with the same breakdown voltage in both common and differential modes.



**Figure 1. Schematic diagram**



### Description

The TPN is a low capacitance transient surge arrester designed for protection of high debit rate communication networks. Its low capacitance avoids distortion of the signal as it has been designed for T1/E1 and Ethernet networks.

**TM:** Trisil is a trademark of STMicroelectronics

# 1 Characteristics

**Table 1. Compliant with the following standards**

	Peak surge voltage (V)	Voltage waveform (µs)	Required peak current (A)	Current waveform (µs)	Minimum serial resistor to meet standard (Ω)
<b>GR-1089-CORE First level</b>	2500	2/10	500	2/10	7.5
	1000	10/1000	100	10/1000	25
<b>GR-1089-CORE Intrabuilding</b>	1500	2/10	100	2/10	0
<b>ITU-T-K20/K21</b>	1000	10/700	25	5/310	0
<b>ITU-T-K20 (IEC 61000-4-2)</b>	6000	1/60 ns	ESD contact discharge		-
	8000		ESD air discharge		-
<b>VDE0433</b>	4000	10/700	100	5/310	40
	2000		50		0
<b>VDE0878</b>	4000	1.2/50	100	1/20	0
	2000		50		0
<b>IEC 61000-4-5</b>	2000	10/700	50	5/310	0
	2000	1.2/50	50	8/20	0

**Table 2. Absolute ratings (T<sub>amb</sub> = 25 °C)**

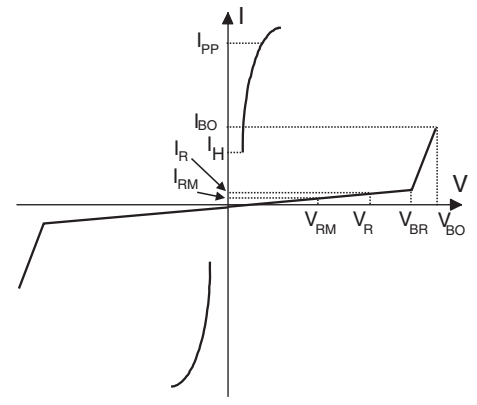
Symbol	Parameter	Value	Unit	
I <sub>PP</sub>	Peak pulse current: t <sub>r</sub> / t <sub>p</sub>	10/1000	30	A
		8/20	100	
		10/560	40	
		5/310	50	
		10/160	75	
		1/20	100	
		2/10	200	
I <sub>TSM</sub>	Non repetitive surge peak on-state current One cycle	50 Hz 60 Hz	8 9	A
	Non repetitive surge peak on-state current (F = 50Hz)	0.2 s 2 s	3 1.5	A
T <sub>stg</sub>	Storage temperature range	-55 to +150	°C	
T <sub>j</sub>	Operating junction temperature range	-40 to +150	°C	
T <sub>L</sub>	Maximum lead temperature for soldering during 10s	260	°C	

**Table 3. Thermal resistances**

Symbol	Parameter	Value	Unit
R <sub>th(j-a)</sub>	Junction to ambient	170	°C/W

**Table 4. Electrical characteristics - definitions ( $T_{amb} = 25^{\circ} C$ )**

Symbol	Parameter
$V_{RM}$	Stand-off voltage
$I_{RM}$	Leakage current at stand-off voltage
$V_R$	Continuous Reverse voltage
$V_{BR}$	Breakdown voltage
$V_{BO}$	Breakover voltage
$I_H$	Holding current
$I_{BO}$	Breakover current
$I_R$	Continuous reverse voltage
$I_{PP}$	Peak pulse current
C	Capacitance

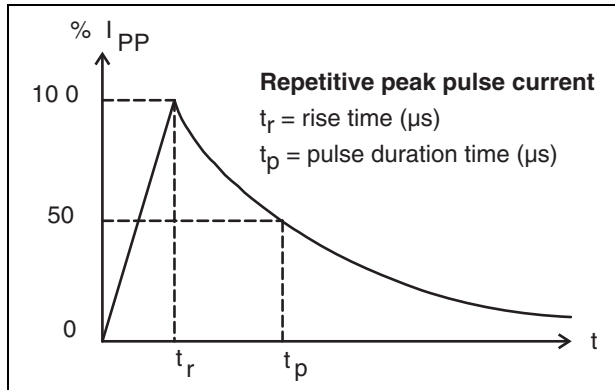


**Table 5. Static parameters**

Order code	$I_{RM}$ max. @ $V_{RM}$		$V_{BO}^{(1)}$ max. @ $I_{BO}$		$I_H^{(2)}$ min.	$C^{(3)}$ typ.
	$\mu A$	V	V	mA	mA	pF
TPN3021	4	28	38	300	30	16

1. See [Figure 6: Test circuit 1 for IBO and VBO parameters](#).
2. See [Figure 7: Test circuit 2 for dynamic IH parameter](#)
3.  $V_R = 0 V$  bias,  $V_{RMS} = 1 V$ ,  $F = 1 MHz$

**Figure 2. Pulse waveform**



**Figure 3. Non repetitive surge peak on-state current versus overload duration ( $T_j$  initial =  $25^{\circ} C$ )**

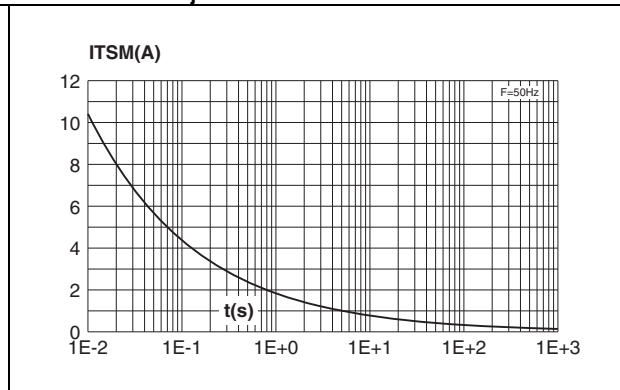


Figure 4. Variation of junction capacitance versus reverse voltage applied (typical values)

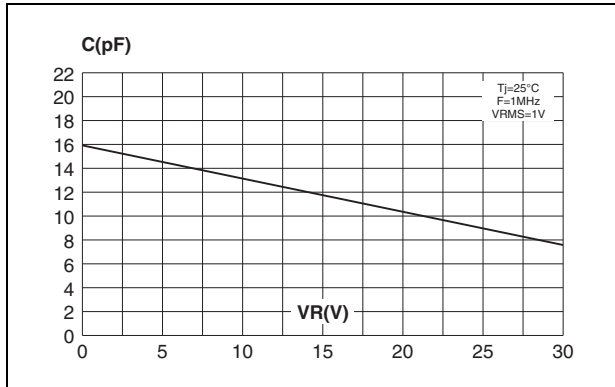
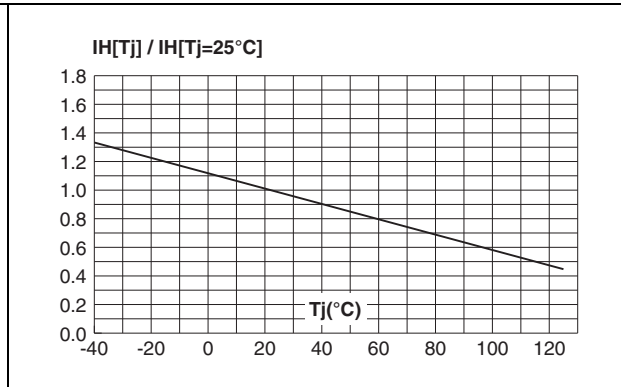


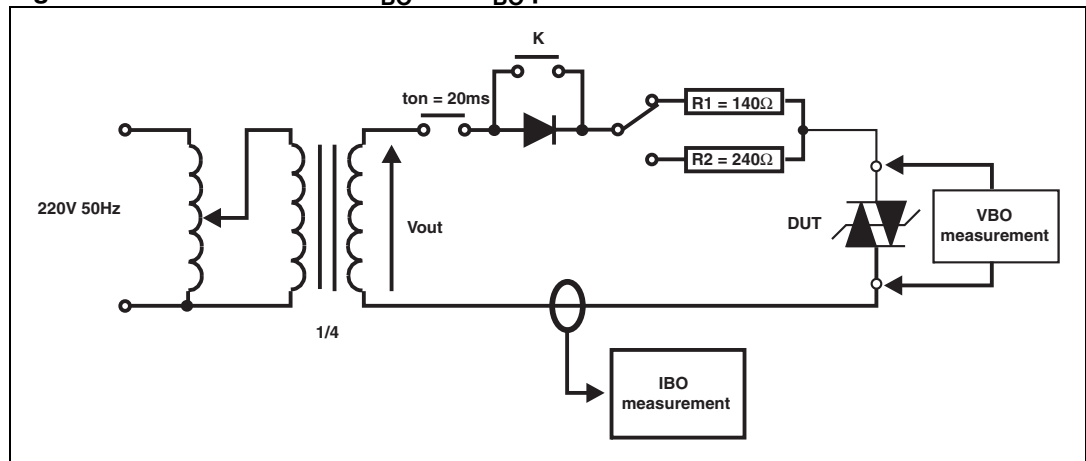
Figure 5. Relative variation of holding current versus junction temperature



## 2 Test circuits

### 2.1 Test procedure for test circuit 1

Figure 6. Test circuit 1 for  $I_{BO}$  and  $V_{BO}$  parameters



Pulse test duration ( $t_p = 20 \text{ ms}$ ):

- For bidirectional devices = switch K is closed
- For unidirectional devices = switch K is open

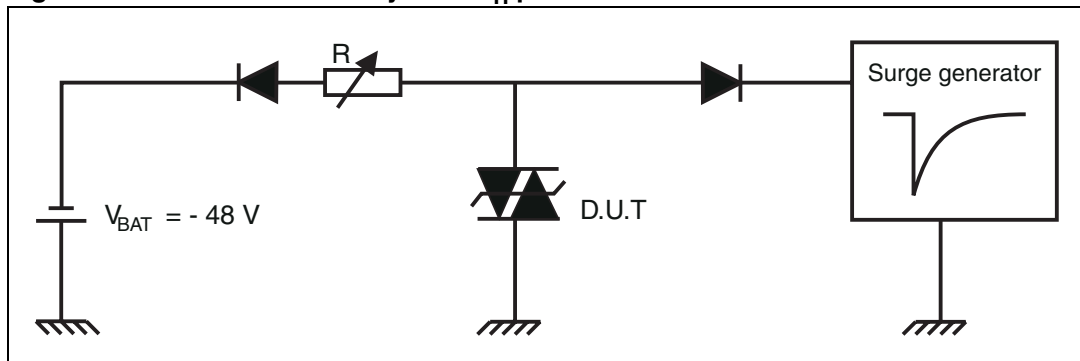
$V_{OUT}$  selection:

Device with  $V_{BO} < 200 \text{ V}$ ,  $V_{OUT} = 250 \text{ V}_{RMS}$ ,  $R1 = 140 \text{ } \Omega$

Device with  $V_{BO} \geq 200 \text{ V}$ ,  $V_{OUT} = 480 \text{ V}_{RMS}$ ,  $R2 = 240 \text{ } \Omega$

## 2.2 Test procedure for test circuit 2

Figure 7. Test circuit 2 for dynamic  $I_H$  parameter



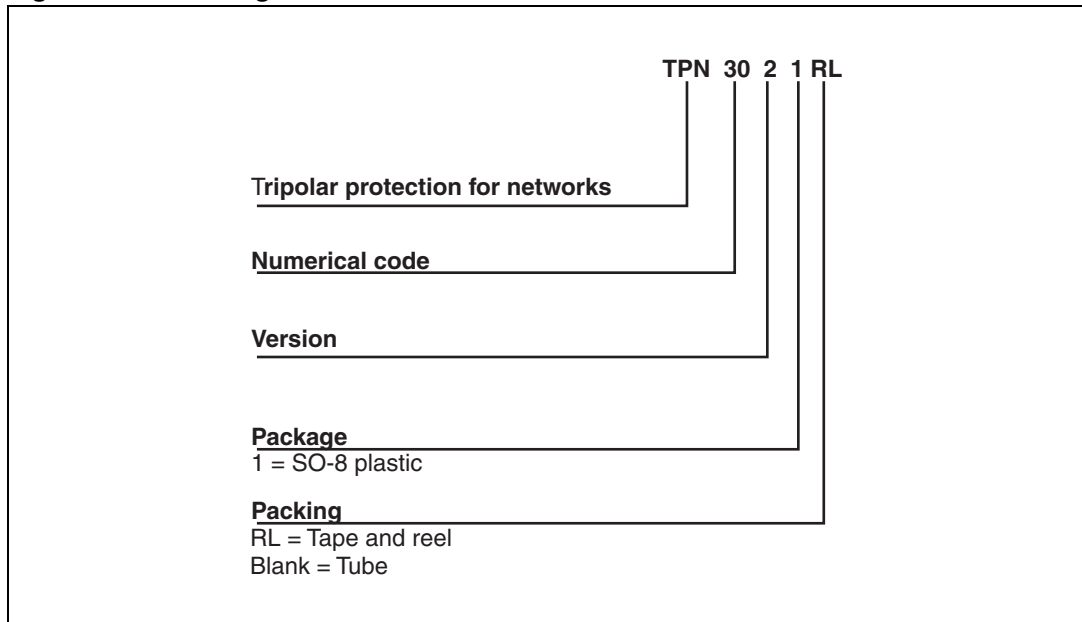
This is a go no-go test, which can confirm the holding current ( $I_H$ ) level.

### Procedure

1. Adjust the current level at the  $I_H$  value by short circuiting the AK of the D.U.T.
2. Fire the D.U.T. with a surge current  $I_{PP} = 10\text{A}$ ,  $10/1000\mu\text{s}$ .
3. The D.U.T. will come back off-state within 50 ms maximum.

### 3 Ordering information scheme

Figure 8. Ordering information scheme



## 4 Package information

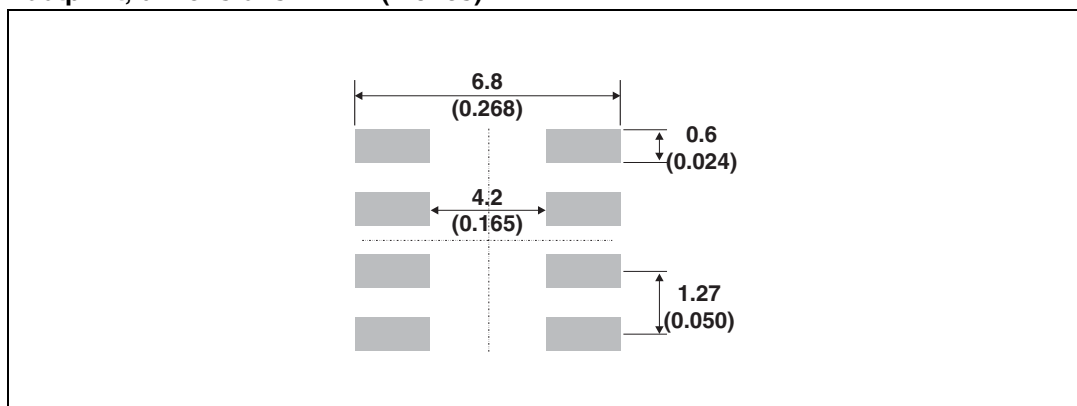
- Epoxy meets UL94, V0
- Lead-free package

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: [www.st.com](http://www.st.com). ECOPACK® is an ST trademark.

**Table 6. SO-8 dimensions**

Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A			1.75			0.069
A1	0.1		0.25	0.004		0.010
A2	1.25			0.049		
b	0.28		0.48	0.011		0.019
C	0.17		0.23	0.007		0.009
D	4.80	4.90	5.00	0.189	0.193	0.197
E	5.80	6.00	6.20	0.228	0.236	0.244
E1	3.80	3.90	4.00	0.150	0.154	0.157
e		1.27			0.050	
h	0.25		0.50	0.010		0.020
L	0.40		1.27	0.016		0.050
L1		1.04			0.041	
k	0°		8°	0°		8°
ppp			0.10			0.004

**Footprint, dimensions in mm (inches)**



## 5 Ordering information

**Table 7. Ordering information**

Ordering code	Marking	Package	Weight	Base qty	Delivery mode
TPN3021	TPN302	SO-8	0.08g	100	Tube
TPN3021RL <sup>(1)</sup>	TPN302			2500	Tape and reel

1. Preferred device

## 6 Revision history

**Table 8. Document revision history**

Date	Revision	Changes
Sep-2001	3	Previous release
07-Feb-2006	4	Reformatted to current template. Maximum junction temperature parameter replaced by Operating junction temperature range in Table 3. Added footnote 1 to Ordering information table.
25-Jun-2010	5	Updated trademark statement.



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### Офис по работе с юридическими лицами:

105318, г.Москва, ул.Щербаковская д.3, офис 1107, 1118, ДЦ «Щербаковский»

Телефон: +7 495 668-12-70 (многоканальный)

Факс: +7 495 668-12-70 (доб.304)

E-mail: [info@moschip.ru](mailto:info@moschip.ru)

Skype отдела продаж:

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